

# 2A, 200V - 1000V Fast Recovery Surface Mount Rectifier

#### **FEATURES**

- Glass passivated chip junction
- Ideal for automated placement
- Low reverse leakage
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- DC to DC converter
- Switching mode converters and inverters
- General purpose

### **MECHANICAL DATA**

• Case: SOD-123FL

• Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

Meet JESD 201 class 1 whisker test

Polarity: Indicated by cathode band

• Weight: 0.016g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	2	Α	
$V_{RRM}$	200 - 1000	V	
I <sub>FSM</sub>	40	Α	
T <sub>J MAX</sub>	150	°C	
Package	SOD-123FL		
Configuration	Single die		









SOD-123FL



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	RS2DFL	RS2GFL	RS2JFL	RS2KFL	RS2MFL	UNIT
Marking code on the devi	Marking code on the device		R2DF	R2GF	R2JF	R2KF	R2MF	
Repetitive peak reverse voltage		$V_{RRM}$	200	400	600	800	1000	V
Reverse voltage, total rms value		$V_{R(RMS)}$	140	280	420	560	700	V
Forward current		I <sub>F</sub>	2				Α	
Surge peak forward current, single half sine-		40						Α
wave superimposed on rated load	t = 1.0ms	I <sub>FSM</sub>	100					Α
Junction temperature		$T_J$	-55 to +150				°C	
Storage temperature		T <sub>STG</sub>	-55 to +150				°C	

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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	R <sub>OJL</sub>	81	°C/W	
Junction-to-ambient thermal resistance	R <sub>OJA</sub>	116	°C/W	
Junction-to-case thermal resistance	R <sub>eJC</sub>	69	°C/W	

**Thermal Performance Note:** Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
	RS2DFL	I <sub>F</sub> = 1A, T <sub>J</sub> = 25°C	V <sub>F</sub>	0.86	-	V
		I <sub>F</sub> = 2A, T <sub>J</sub> = 25°C		0.94	1.30	V
	RS2GFL	I <sub>F</sub> = 1A, T <sub>J</sub> = 125°C		0.75	-	V
<b>F</b> (1)		I <sub>F</sub> = 2A, T <sub>J</sub> = 125°C	]	0.84	0.99	V
Forward voltage <sup>(1)</sup>		I <sub>F</sub> = 1A, T <sub>J</sub> = 25°C		0.98	-	V
	RS2JFL	I <sub>F</sub> = 2A, T <sub>J</sub> = 25°C	V <sub>F</sub>	1.09	1.30	V
	RS2KFL RS2MFL	I <sub>F</sub> = 1A, T <sub>J</sub> = 125°C		0.89	-	V
		I <sub>F</sub> = 2A, T <sub>J</sub> = 125°C		1.02	1.20	V
- (2)		T <sub>J</sub> = 25°C		-	5	μΑ
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>		T <sub>J</sub> = 125°C	- I <sub>R</sub>	-	150	μΑ
RS2DFL RS2GFL		1 050 1 100	1.00	-	150	ns
Reverse recovery time	RS2JFL RS2KFL RS2MFL	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$	t <sub>rr</sub>	-	250	ns
	RS2DFL RS2GFL		CJ	16	-	pF
Junction capacitance	RS2JFL RS2KFL RS2MFL	1MHz, V <sub>R</sub> = 4.0V		9	-	pF

### Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING	
RS2xFL	SOD-123FL	10,000 / Tape & Reel	

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### Notes:

1. "x" defines voltage from 200V(RS2DFL) to 1000V(RS2MFL)



### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

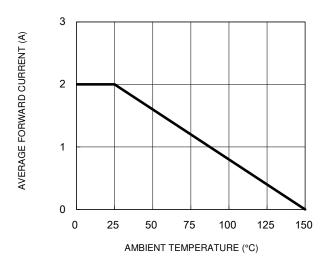


Fig.3 Typical Reverse Characteristics

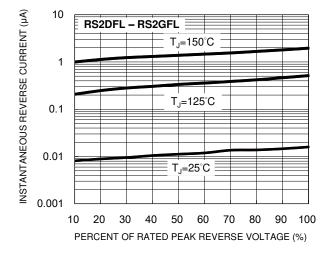


Fig.5 Typical Reverse Characteristics

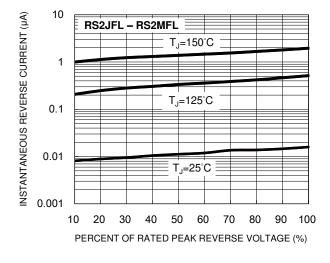


Fig.2 Typical Junction Capacitance

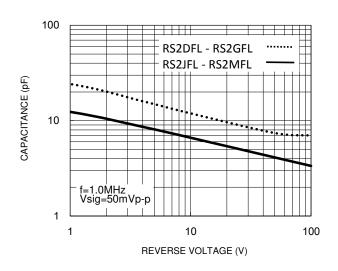


Fig.4 Typical Forward Characteristics

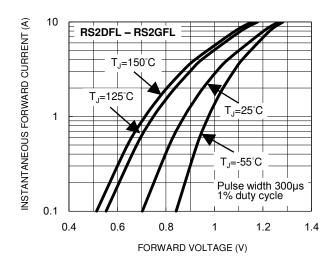
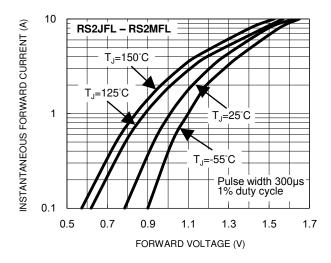


Fig.6 Typical Forward Characteristics

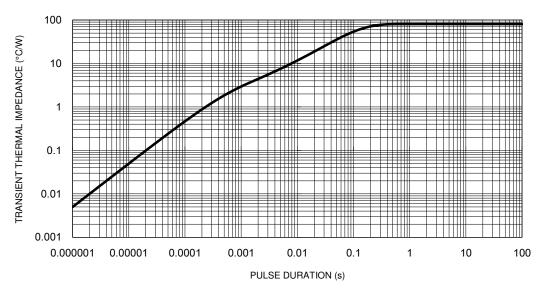




### **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

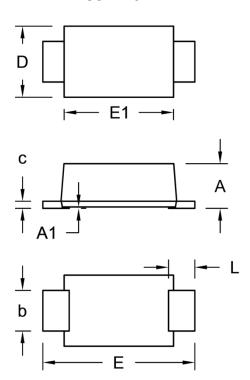
Fig.7 Typical Transient Thermal Impedance





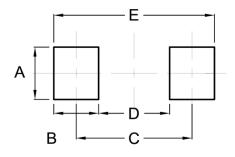
# **PACKAGE OUTLINE DIMENSIONS**

SOD-123FL



DIM.	Unit	(mm)	Unit (inch)	
Dilvi.	Min.	Max.	Min.	Max.
Α	1.00	1.20	0.039	0.047
A1	0.02	0.05	0.001	0.002
b	0.90	1.10	0.035	0.043
С	0.10	0.25	0.004	0.010
D	1.60	1.90	0.063	0.075
E	3.60	3.90	0.142	0.154
E1	2.55	2.85	0.100	0.112
L	0.40	0.90	0.016	0.035

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	1.40	0.055
В	1.20	0.047
С	3.10	0.122
D	1.90	0.075
E	4.30	0.169

## **MARKING DIAGRAM**



P/N = Marking Code = Date Code ΥW F = Factory Code



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